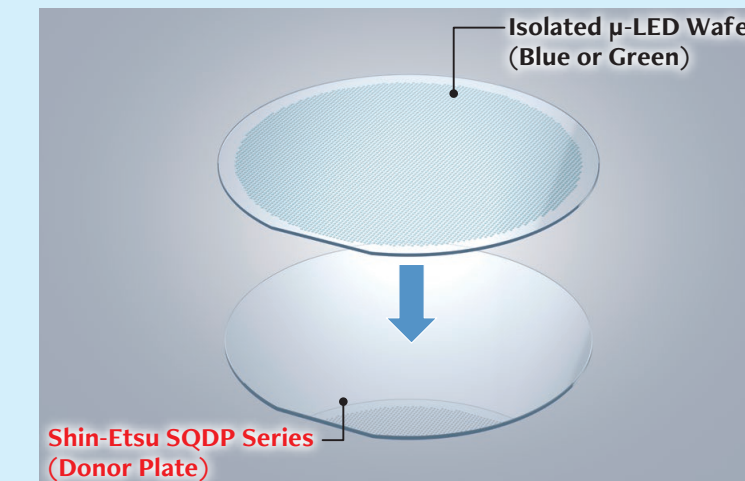


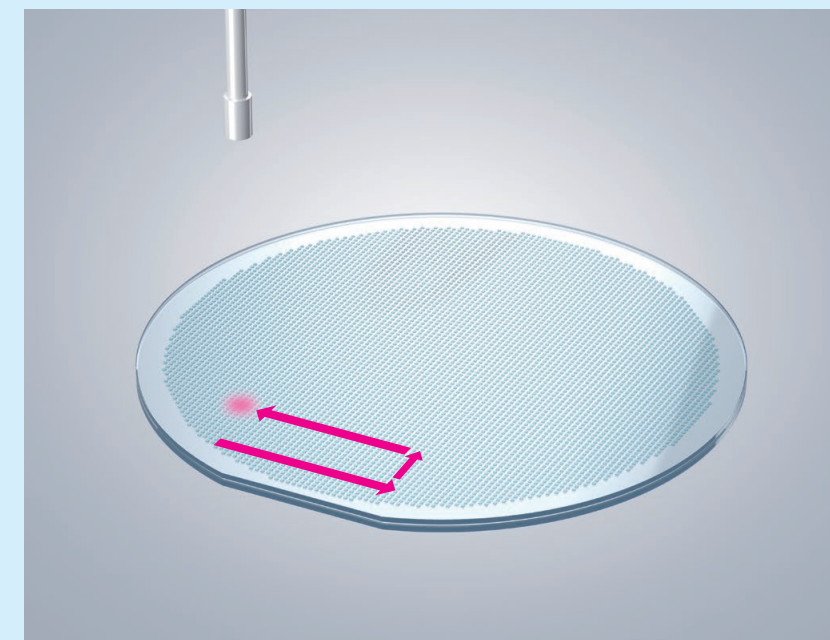
μ -LED Chip Process from LLO (Laser Lift Off) to Mass Transfer

ShinEtsu

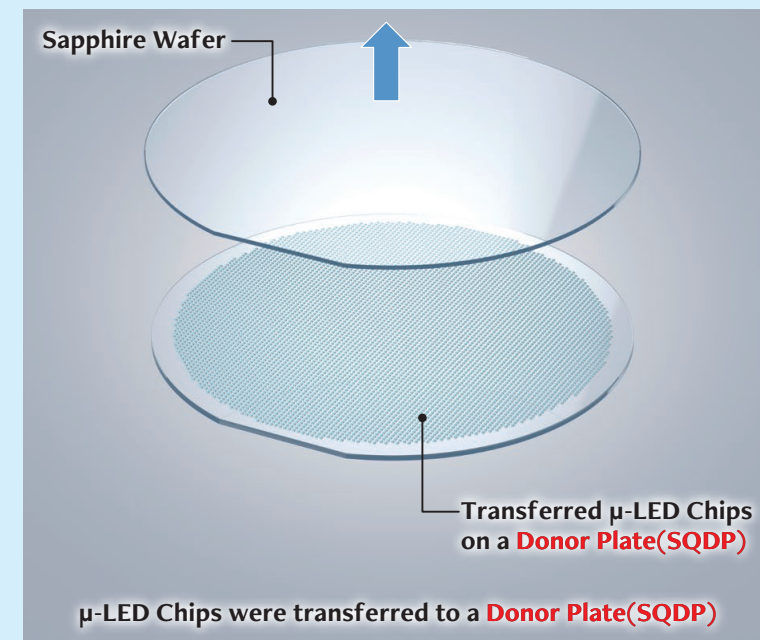
① LED Wafer Attached on a Donor Plate



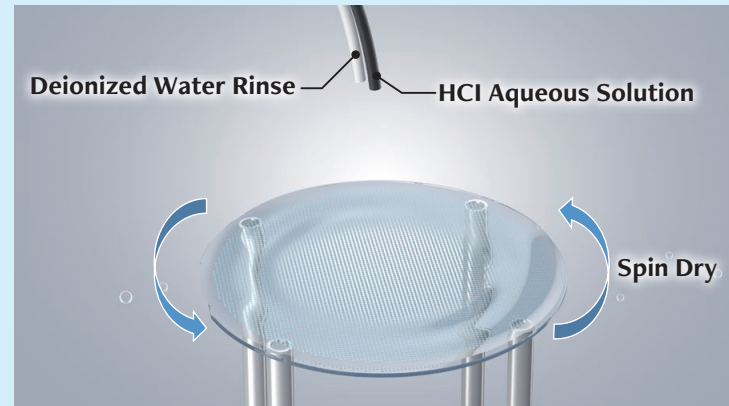
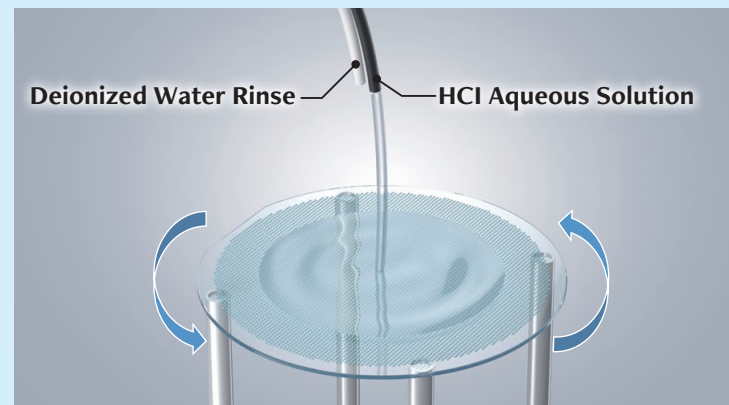
② Laser Lift Off Process



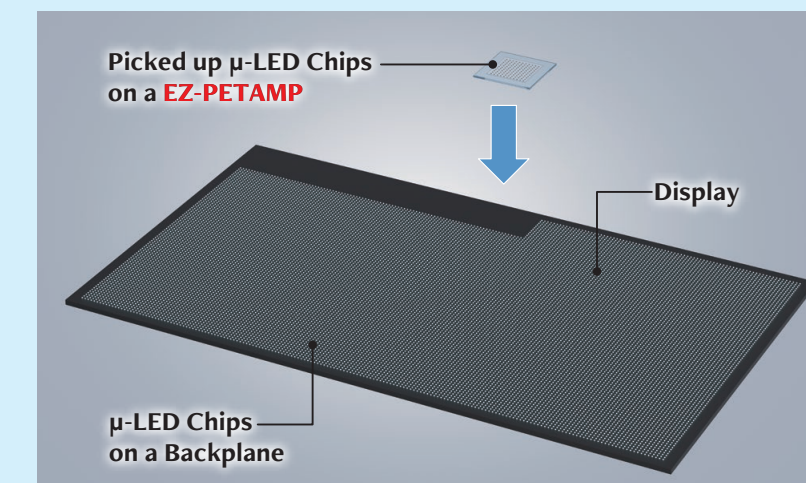
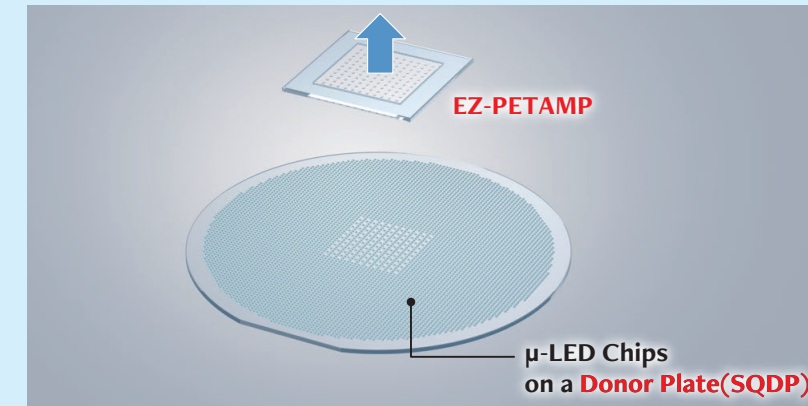
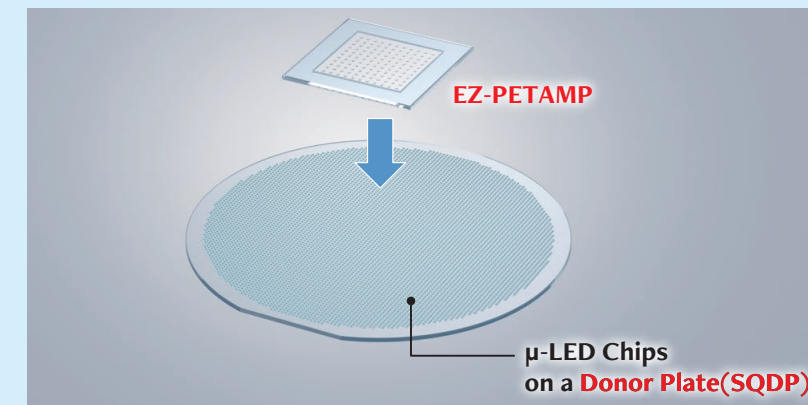
③ Removal of Sapphire Wafer



④ Ga Cleaning Process



⑤ μ -LED Chip Mass Transfer Process



⑥ μ -LED Lit

